IN THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-7 (Canceled).

8. (Currently Amended) Method for making a sensor of physical quantities comprising:

preparing an active sensor part and a base, the active part comprising at least one wafer provided with conductive connection pads on a first face and the base provided with conductive pins;

electrically connecting the pads and the pins by conductive elements;

plunging the wafer and ends of the pins into an electrolytic bath;

performing an electrolytic deposition of at least one conductive metal on the pin ends, the connection pads, and the conductive elements that connect them; and

performing an oxidizing or nitrizing operation on ~~this~~ the metal to make an insulating coat on the connection pads, the pin ends, and the conductive elements that connect them.

9. (Previously Presented) Method according to claim 8, wherein the electrolytic deposition is obtained by migration of metal ions coming from a liquid solution, with passage of electrical current into the solution.

10. (Previously Presented) Method according to claim 8, wherein the electrolytic deposition is an electroless deposition carried out by migration of metal ions coming from a liquid solution, without passage of electrical current.

11. (Currently Amended) Method according to claim 8, wherein the electrolytically deposited conductive metal is one of nickel, tantalum, ~~or~~ tungsten or molybdenum.

12. (Currently Amended) Method according to claim 8, wherein the ~~pins and the connection pads~~ conductive elements are ~~connected by~~ bonded wires.

13. (Previously Presented) Method according to claim 8, wherein the conductive elements that connect the pads electrically and mechanically to the pins includes an electrolytic metal deposit.

14. (Previously Presented) Sensor of physical quantities obtained by the method of claim 8, wherein the sensor constitutes a sensor of pressure, stresses, acceleration, temperature, gas or liquid.